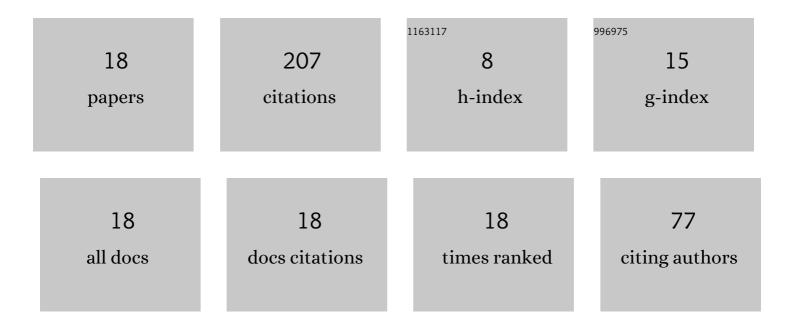
Tarik Omer Ogurtani

List of Publications by Year in descending order

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| # | Article | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Effects of anisotropic surface drift diffusion on the strained heteroepitaxial nanoislands subjected to electromigration stressing. Journal of Applied Physics, 2022, 131, 075301. | 2.5 | 1 |
| 2 | Mesoscopic irreversible thermodynamics of morphological evolution kinetics of helical conformation in bioproteins â€~DNA' under the isothermal isobaric conditions. , 2020, 4, 009-019. | | 2 |
| 3 | Grain boundary grooving in bi-crystal thin films induced by surface drift-diffusion driven by capillary forces and applied uniaxial tensile stresses. Philosophical Magazine, 2012, 92, 804-829. | 1.6 | 8 |
| 4 | Mesoscopic nonequilibrium thermodynamics treatment of the grain boundary thermal grooving induced by the anisotropic surface drift diffusion. Journal of Materials Science, 2011, 46, 6054-6064. | 3.7 | 6 |
| 5 | Morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate: Dynamical simulations. Journal of Applied Physics, 2010, 108, . | 2.5 | 8 |
| 6 | Generic role of the anisotropic surface free energy on the morphological evolution in a strained-heteroepitaxial solid droplet on a rigid substrate. Journal of Applied Physics, 2010, 108, . | 2.5 | 6 |
| 7 | Thermal grain-boundary grooving in bicrystal thin solid films having strong anisotropic surface Gibbs free energy represented by the modified cycloid-curtate function. Journal of Crystal Growth, 2009, 311, 1584-1593. | 1.5 | 7 |
| 8 | Cathode edge displacement by voiding coupled with grain boundary grooving in bamboo like metallic interconnects by surface drift-diffusion under the capillary and electromigration forces. International Journal of Solids and Structures, 2008, 45, 921-942. | 2.7 | 9 |
| 9 | Morphological evolution of voids by surface drift diffusion driven by capillary, electromigration, and thermal-stress gradients induced by steady-state heat flow in passivated metallic thin films and flip chip solder joints. I. Theory. Journal of Applied Physics, 2008, 104, 023521. | 2.5 | 14 |
| 10 | Morphological evolution of edge-hillocks on single-crystal films having anisotropic drift-diffusion under the capillary and electromigration forces. Thin Solid Films, 2007, 515, 2974-2983. | 1.8 | 8 |
| 11 | Unified theory of linear instability of anisotropic surfaces and interfaces under capillary, electrostatic, and elastostatic forces: The regrowth of epitaxial amorphous silicon. Physical Review B, 2006, 74, . | 3.2 | 22 |
| 12 | Variational formulation of irreversible thermodynamics of surfaces and interfaces with grain-boundary triple-junction singularities under the capillary and electromigration forces in anisotropic two-dimensional space. Physical Review B, 2006, 73, . | 3.2 | 16 |
| 13 | Computer Simulations on the Grain Boundary Grooving and Cathode Edge Displacement in Bamboo-like Metalic Interconnects. Materials Research Society Symposia Proceedings, 2006, 914, 1. | 0.1 | 1 |
| 14 | Mesoscopic nonequilibrium thermodynamics of solid surfaces and interfaces with triple junction singularities under the capillary and electromigration forces in anisotropic three-dimensional space. Journal of Chemical Physics, 2006, 124, 144706. | 3.0 | 31 |
| 15 | Irreversible thermodynamics of triple junctions during the intergranular void motion under the electromigration forces. International Journal of Solids and Structures, 2005, 42, 3918-3952. | 2.7 | 35 |
| 16 | The Effect of Initial Void Configuration on the Morphological Evolution Under the Action of Normalized Electron Wind Forces. Materials Research Society Symposia Proceedings, 2001, 714, 921. | 0.1 | 0 |
| 17 | Void Intergranual Motion Under the Action of Electromigration Forces in Thin Film Interconnects with Bamboo Structure. Materials Research Society Symposia Proceedings, 2001, 695, 1. | 0.1 | 4 |
| 18 | Computer simulation of void growth dynamics under the action of electromigration and capillary forces in narrow thin interconnects, Journal of Applied Physics, 2001, 90, 1564-1572. | 2.5 | 29 |